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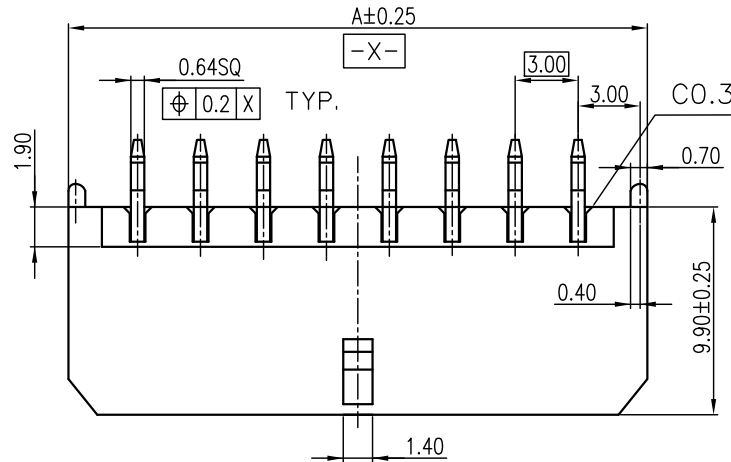
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	07/04/2006	Armstrong Kao
B	NE-06295	MODIFIED DRAWING	09/06/2006	Edward Wu
C	NE-09209	MODIFIED DRAWING	12/30/2009	Arron Lin
D	NE-10003	MODIFIED DRAWING	01/07/2010	Arron Lin
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010	Roger Tsai
F	NE-11043	MODIFIED DRAWING	03/28/2010	Arron Lin
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011	Arron Lin
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011	Arron Lin
C1	NE-12012	ADDED POST DIM. 0.95	01/31/2012	Arron Lin
D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012	Arron Lin
E1	NE-12113	REMOVE 2 POS OPTIONS AND UPDATE PACKING QUANTITY.	07/04/2012	Arron Lin
F1	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
A2	NE-13197	ADDED DIM & UPDATE FINISH NOTE	12/06/2013	Arron Lin
B2	NE-15054	ADD 2PIN AND UPDATE PACKING	04/29/2015	Roger Tsai

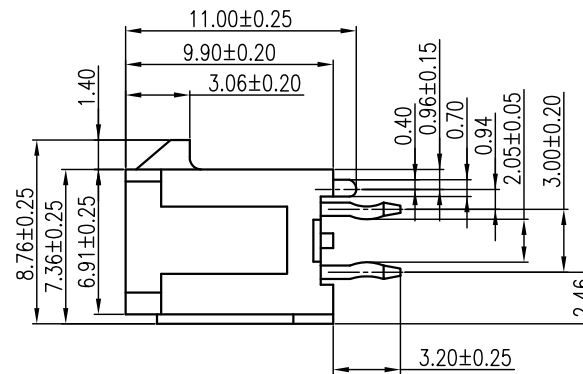
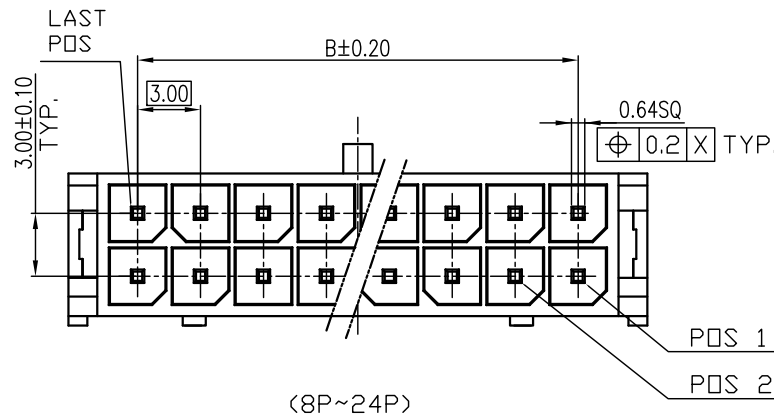


PART NO. G881AXX1X2TEU
No. OF CIRCUIT

CONTACT FINISH
0: Tin (OVERALL)
1: FLASH GOLD (OVERALL)
2: 15 u" GOLD
3: 30 u" GOLD

NOTE:

- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
- CONTACT MATERIAL: COPPER ALLOY;
- FINISH:
CONTACT: SELECTIVE PLATING. ;
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC FOR RoHS.
- PACKING MUST BE PER Amphenol PACKING SPECIFICATION



24	39.60	33.00
22	36.60	30.00
20	33.60	27.00
18	30.60	24.00
16	27.60	21.00
14	24.60	18.00
12	21.60	15.00
10	18.60	12.00
08	15.60	9.00
06	12.60	6.00
04	9.60	3.00
02	6.60	
NO. OF CIRCUIT	A	B

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30	DRAWN Aqua Chou	04/29/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT	mm	A3	G881AXX1X2TEU
X.X ±0.20	CHECKED Roger Tsai	04/29/2015				
X.XXX ±0.10	APPROVED Roger Tsai	04/29/2015				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD		SCALE NA	SHEET 1 OF 3	
UNLESS OTHERWISE SPECIFIED						REV. B2

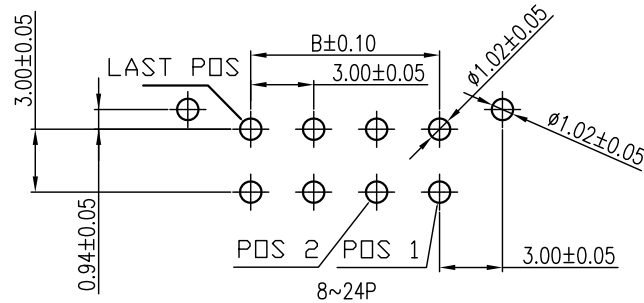
Amphenol[®]
Amphenol Corporation
Amphenol Taiwan Corporation

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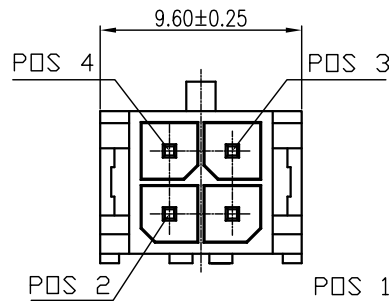
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ORIGINAL

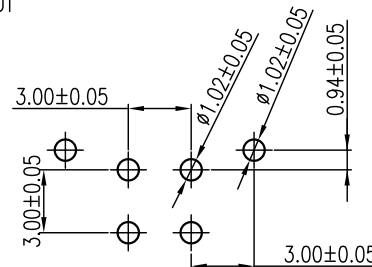
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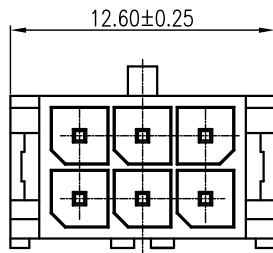
RECOMMENDED PCB LAYOUT
(THICKNESS: 1.60mm)



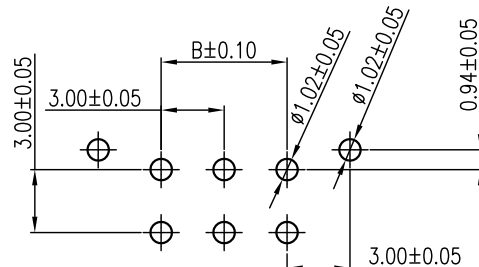
(2X2POS)



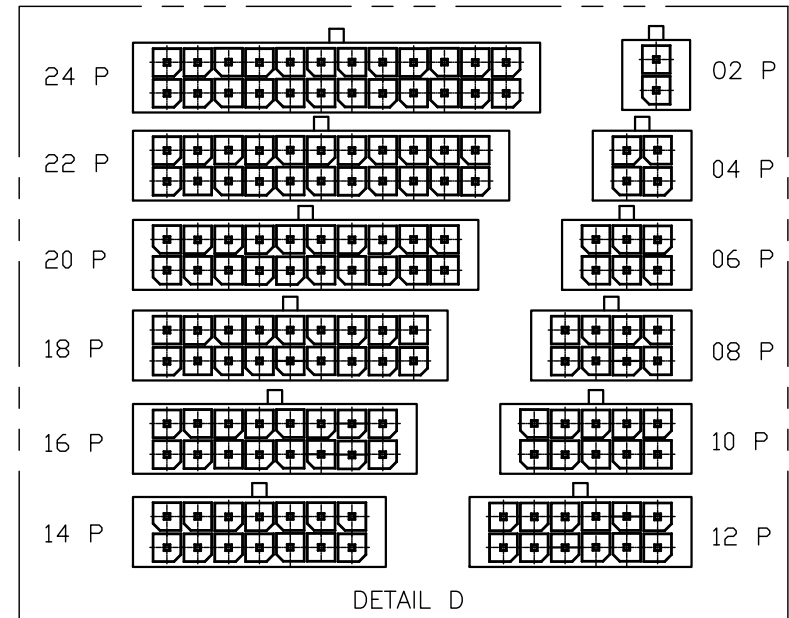
2X2POSITIONS
RECOMMENDED PCB LAYOUT
(THICKNESS: 1.60mm)



(2X3POS)



2X3POSITIONS
RECOMMENDED PCB LAYOUT
(THICKNESS: 1.60mm)



DETAIL D

TOLERANCE	APPROVALS	DATE	TITLE		PART No.	
X.	DRAWN Aqua Chou	04/29/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.30	CHECKED Roger Tsai	04/29/2015				
X.XX ±0.20	APPROVED Roger Tsai	04/29/2015	UNLESS OTHERWISE SPECIFIED		UNIT mm	SIZE A3
X.XXX ±0.10	DWG TYPE CUST DWG	PROJECT CODE PHD			SCALE NA	SHEET 2 OF 3
ANGULAR ±1°					DWG No. G881AXX1X2TEU	REV. B2

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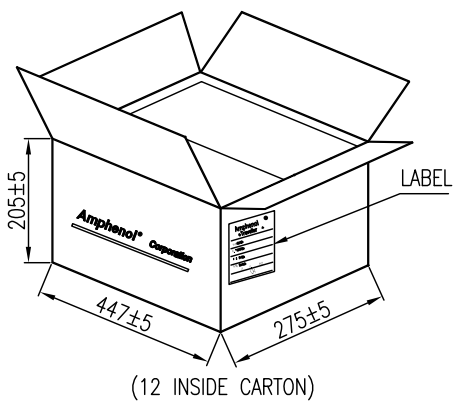
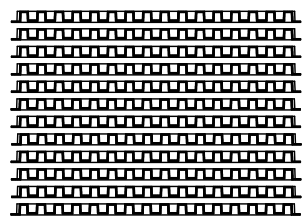
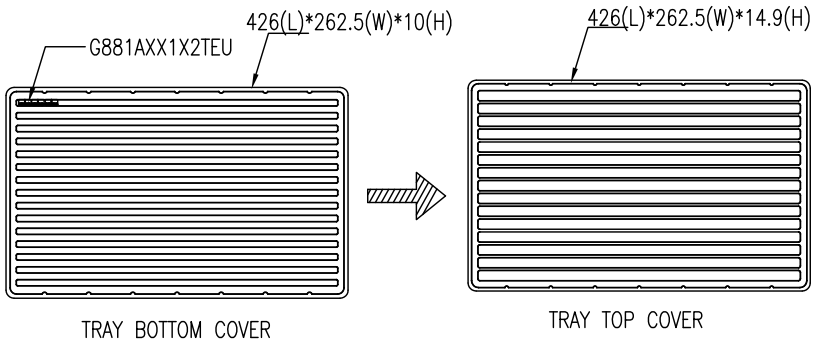
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POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:
 1. MATERIAL : TRANSPARENT CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE		APPROVALS		DATE	TITLE			Amphenol [®]			
X.		DRAWN	Aqua Chou	04/29/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT			Amphenol Corporation Amphenol Taiwan Corporation			
X.X	±0.30	CHECKED	Roger Tsai	04/29/2015							
X.XX	±0.20	APPROVED	Roger Tsai	04/29/2015							
X.XXX	±0.10							PART No. G881AXX1X2TEU			
ANGULAR	±1°							DVG No. G881AXX1X2TEU			
UNLESS OTHERWISE SPECIFIED		DWG TYPE		PROJECT CODE				REV. B2			
		CUST DWG		PHD	UNIT	mm	SIZE	A3			
					SCALE	NA	SHEET	3 OF 3			